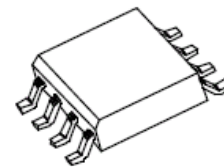


**TVS ARRAY SERIES**

**FEATURES**

- ✓ Protects 3.3, 5, 12, 15, 24 V Components
- ✓ Bidirectional
- ✓ Ultra Low Capacitance 3 pF
- ✓ Provides Electrically Isolated Protection
- ✓ 500 W @ 8/20  $\mu$ s
- ✓ Protects 2 Lines
- ✓ SO-8 Packaging
- ✓ This is a Pb - Free Device
- ✓ All SMC parts are traceable to the wafer lot
- ✓ Additional testing can be offered upon request

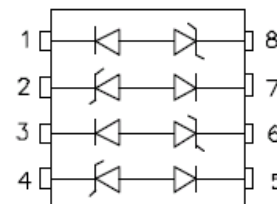
**SO-8**



**DESCRIPTION**

The S8ULCCXX-2 series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect up to 2 bidirectional lines.

**SCHEMATIC & PIN CONFIGURATION**



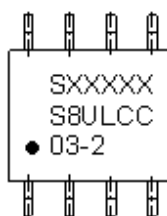
**APPLICATION**

- ✓ 10/100 Base T Ethernet
- ✓ USB
- ✓ Cellular Phone Terminals
- ✓ Audio/Video Inputs
- ✓ xDSL Interfaces

**MECHANICAL CHARACTERISTICS**

- ✓ SO-8 Surface Mount Package
- ✓ Approximate Weight: 0.1 grams
- ✓ PIN #1 Indicator: DOT on top of package
- ✓ Packaging: Tubes or Tape & Reel per EIA Standard 481

**MARKING DIAGRAM**



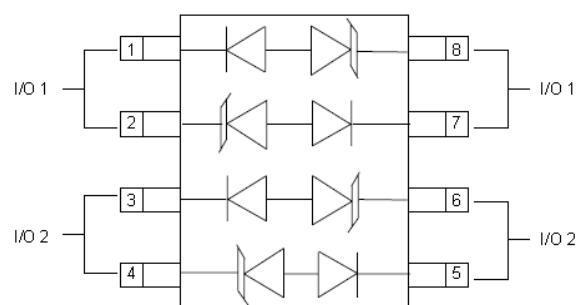
Where XXXXX is YYWWL

S8ULCC03-2 = Part Name  
 S = S  
 YY = Year  
 WW = Week  
 L = Lot Number

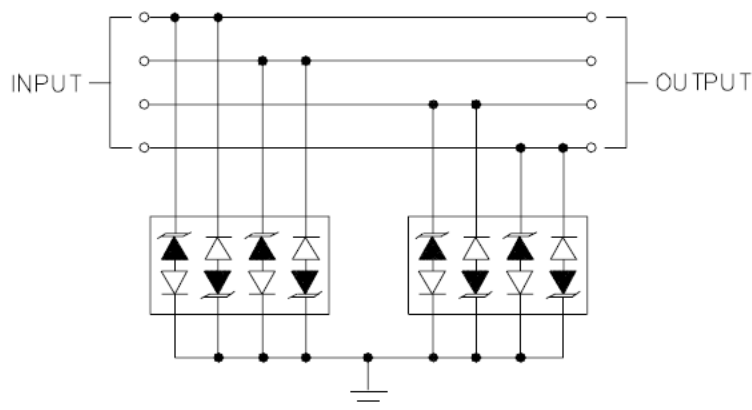
**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - [sales@smc-diodes.com](mailto:sales@smc-diodes.com) •

**Circuit Diagram**



**I/O Line Protection**



**Connection Options**

The devices are connected as follows:

- ✓ Pins 1, 2, 7, and 8 are used to protect one data line. Pins 3, 4, 5, and 6 are used to protect the second data line.
- ✓ Pins 1 and 2 are tied together and pins 7 and 8 are tied together providing the protection circuit for one I/O line. Pins 3 and 4 are tied together and pins 5 and 6 are tied together providing the protection circuit for the second I/O line. Since the device is electrically symmetrical, either side of the connected pairs may be used to protect the lines. The other side of the pair is used to make the ground connection. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.

**Ordering Information:**

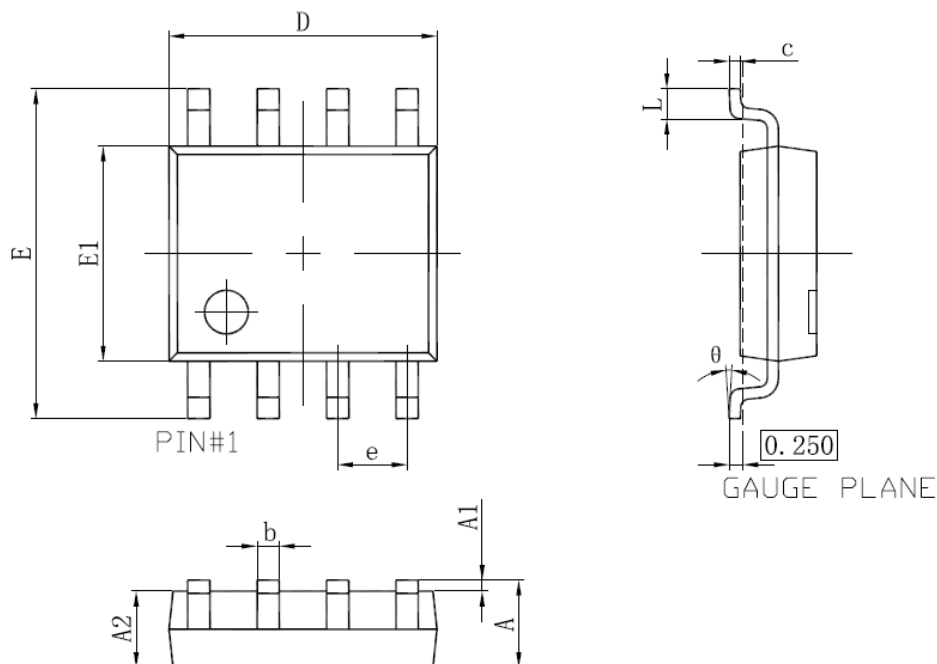
Device	Package	Shipping
S8ULCC03-2 THRU S8ULCC24-2	SO-8 (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20 μ s)	P <sub>pp</sub>	500	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature	T <sub>J</sub>	-55 to 125	°C
Lead Soldering Temperature	T <sub>L</sub>	260(10Sec.)	°C

PACKAGE OUTLINES & DEMENSIONS



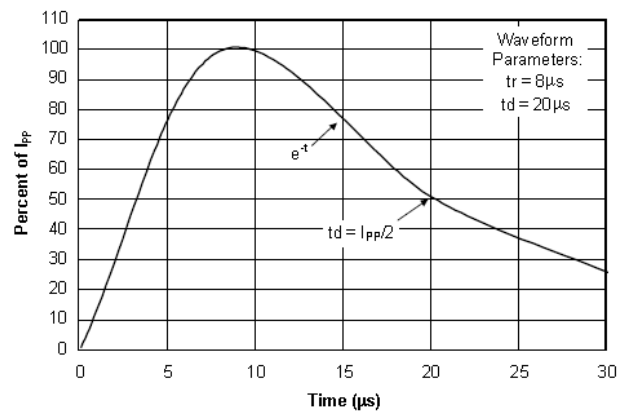
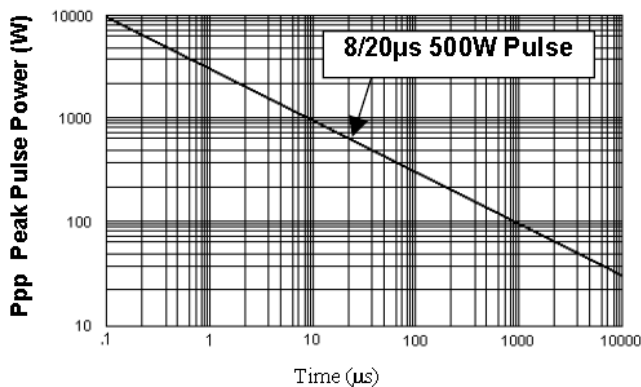
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
theta	0°	8°	0°	8°

SO-8(CJ)

**ELECTRICAL CHARACTERISTICS @ 25 °C**

Part Number	Stand-off Voltage $V_{wm}$ (v) Max	Breakdown Voltage $V_{BR}$ @1mA (V) Min	Clamping Voltage $V_c$ @ 1 A (V) Max	Leakage Current $I_R$ @ $V_{wm}$ ( $\mu$ A) Max	Capacitance (f = 1 MHz) C @ 0V (pF) Max	Temperature Coefficient of $V_{BR}$ $a(V_{BR})$ mV/°C Max
S8ULCC03-2	3.3	4	8	200	5	-5
S8ULCC05-2	5.0	6	9.8	20	5	1
S8ULCC12-2	12.0	13.3	19	1	5	8
S8ULCC15-2	15.0	16.7	24	1	5	11
S8ULCC24-2	24.0	26.7	43	1	5	28

**TYPICAL CHARACTERISTICS**





S8ULCC03-2  
THRU  
S8ULCC24-2

**Technical Data**  
**Data Sheet N0286, Rev. A**

***Green Products***

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